

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4	"6815614"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 21:23
L2	391	"257"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and pad and bar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:11
L3	1	("4916413").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 21:54
L4	52	"257"/\$.ccls. and (MLF micro adj lead adj frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:23
L5	52	(MLF micro adj lead adj frame) and (passive capacitor resistor inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:18
L6	63	"361"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and pad and bar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:23
L7	370	"361"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:00
L8	13	("4447716" "4611882" "5067008" "5736781" "5821457" "5963796" "5974504" "5982030" "5986341" "5998860" "5998865" "6013948" "6072122").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 22:04
L9	697	"438"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:12

L10	618	"438"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:21
L11	113	"438"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad) and bar	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:12
L12	337	(MLF micro adj lead adj frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:18
L13	49	(micro adj lead adj frame)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:18
L14	2085	"257"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:24
L15	1849	"257"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad) and wire	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:24
L16	1355	"257"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad) and wire and (resin epoxy molding adj compound encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:26
L17	1334	"257"/\$.ccls. and (passive capacitor resistor inductor) and lead adj frame and (electrode pad) and wire and (resin epoxy molding adj compound encapsulant) and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 22:27
L18	692	"257"/\$.ccls. and (passive capacitor resistor inductor) same (electrode pad) and lead adj frame and wire and (resin epoxy molding adj compound encapsulant) and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 23:17
L19	1	("6608375").PN.	USPAT	OR	OFF	2005/06/26 22:30
L20	5	("4714952" "5378656" "5637913" "5962917" "6400007").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 22:32

L21	1	("3791025").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 22:48
L22	6	("3271625" "3325586" "3544857").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 22:51
L23	1	jp-2000307397-\$.did.	JPO	OR	OFF	2005/06/26 22:51
L24	4	("20020033530" "5428885" "5504372" "6358780").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 22:59
L25	8	("5559364" "5580466" "6001671" "6025650" "6063139" "6228676" "6410363" "6451627").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 23:05
L26	62	("2600343" "2777110" "2885601" "2896028" "3168704" "3264569" "3316458" "3437943" "3489952" "3537022" "3593208" "3614832" "3675095" "3679941" "3714540" "3745508" "3757175" "3764938" "3833838" "4023053" "4038488" "4117411" "4143508" "4167647" "4173033" "4178556" "4188651" "4193028" "4249135" "4292595" "4376274" "4391531" "4410905" "4506108" "4536638" "4551747" "4561039" "4600907" "4622619" "4680613" "4697858" "4705917" "4748419" "4780795" "4835486" "4974054" "4991001" "5057805" "5229640" "5233220" "5302921").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/06/26 23:10
L27	198	"438"/\$.ccls. and (passive capacitor resistor inductor) same (electrode pad) and lead adj frame and wire and (resin epoxy molding adj compound encapsulant) and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 23:19
L28	207	"361"/\$.ccls. and (passive capacitor resistor inductor) same (electrode pad) and lead adj frame and wire and (resin epoxy molding adj compound encapsulant) and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 23:21

L29	83	"29"/\$.ccls. and (passive capacitor resistor inductor) same (electrode pad) and lead adj frame and wire and (resin epoxy molding adj compound encapsulant) and (chip die ic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 23:21
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